

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6018015

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
EMMA BOUGHAN	03/03/2020
BENJAMIN A. HOLTSBERRY	03/05/2020
PHILLIP MICHAEL GONZALES	03/04/2020
RECEIVING PARTY DATA	
Name:	HONDA MOTOR CO., LTD.
Street Address:	NO. 1-1, MINAMI-AOYAMA 2-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16821270
CORRESPONDENCE DATA	
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Address Line 4:	WASHINGTON, D.C. 20007
ATTORNEY DOCKET NUMBER:	3009-0380
NAME OF SUBMITTER:	DAVID J. KENEALY
SIGNATURE:	/davidjkenealy/
DATE SIGNED:	03/17/2020
Total Attachments: 4	
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ASSIGNMENT

WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

APPARATUS AND METHOD FOR INSTALLING GROMMETS IN A VEHICLE

for which WE executed an application for United States Letters Patent concurrently herewith; and

WHEREAS Honda Motor Co., Ltd., a corporation of Japan, whose post office address is No. 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo, Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

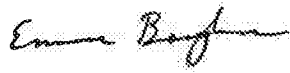
AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys empowered by Honda Motor Co., Ltd. in this application, to insert here in parentheses (Application No. 16/821,270, filed 17-MAR-2020) the filing date and application number of said application when known.

KENEALY VAIDYA LLP

PATENT
REEL: 052139 FRAME: 0549

IN TESTIMONY WHEREOF, I have hereunto set my hand.

<u>Full Name of First Assignor</u> Emma Boughan	<u>Assignor's Signature</u> 	<u>Date</u> 3-3-20
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America
<u>Full Name of Second Assignor</u> Benjamin A Holtzberry	<u>Assignor's Signature</u>	<u>Date</u>
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America
<u>Full Name of Third Assignor</u> Phillip Michael Gonzales	<u>Assignor's Signature</u>	<u>Date</u>
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America

NAMES OF ADDITIONAL INVENTORS ATTACHED YES NO

KENEALY VAIDYA LLP

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<u>Full Name of Second Assignor</u> Benjamin A Holtsherry	<u>Assignor's Signature</u> 	<u>Date</u> 3/5/20
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America
<u>Full Name of Third Assignor</u> Phillip Michael Gonzales	<u>Assignor's Signature</u> 	<u>Date</u>
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America

NAMES OF ADDITIONAL INVENTORS ATTACHED | YES NO

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<u>Full Name of Second Assignor</u> Benjamin A Holtsberry	<u>Assignor's Signature</u> 	<u>Date</u>
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America
<u>Full Name of Third Assignor</u> Phillip Michael Gonzales	<u>Assignor's Signature</u> 	<u>Date</u> 3/4/2020
<u>Address:</u> c/o Honda Patents & Technologies North America, LLC 21001 State Route 739, Raymond, Ohio 43067-9705		<u>Citizenship:</u> United States of America

NAMES OF ADDITIONAL INVENTORS ATTACHED [] YES [X] NO

KENEALY VAIDYA LLP

PATENT